

## AMENDMENTS TO THE CLAIMS

Please amend the claims as follows:

Claim 1 (currently amended): A composite substance ~~for forming a conductive paste,~~  
comprising:

a solvent which is compatible with an organic component included in ~~said a~~  
conductive paste; and metal particles wetted by said solvent,

wherein said composite substance is prepared by mixing the solvent with undried  
metal particles.

Claim 2 (cancelled)

Claim 3 (previously amended): The composite substance of claim 1, wherein:  
said metal particles have an average particle size of 1  $\mu\text{m}$  or smaller.

Claim 4 (previously amended): The composite substance of claim 1, wherein:  
the solvent comprises 2 to 100 parts by weight of the composite substance relative to  
100 parts by weight of said metal particles.

Claim 5 (cancelled)

Claim 6 (currently amended): A composite substance ~~for forming a conductive paste,,~~  
comprising:

a solvent which is compatible with an organic component included in ~~said a~~  
conductive paste; and

metal-compound particles wetted by said solvent, wherein said composite substance is prepared by mixing the solvent with undried metal-compound particles.

Claim 7 (cancelled)

Claim 8 (previously amended): The composite substance of claim 6, wherein:  
said metal-compound particles have an average particle size of 1  $\mu\text{m}$  or smaller.

Claim 9 (previously amended): The composite substance of claim 6, wherein:  
the solvent comprises 2 to 100 parts by weight of the composite substance relative to  
100 parts by weight of said metal-compound particles.

Claim 10 (cancelled)

Claim 11 (previously amended): A conductive paste comprising:  
an organic binder;  
a composite substance comprising a solvent which is compatible with said organic  
binder, and metal particles wetted by said solvent; and  
an organic solvent mixed with said organic binder and said composite substance  
wherein said composite substance is prepared by mixing the solvent with undried  
metal particles.

Claim 12 (cancelled)

Claim 13 (previously amended): The conductive paste of claim 11, wherein:

said metal particles have an average particle size of 1  $\mu\text{m}$  or smaller.

Claim 14 (previously amended): The conductive paste of claim 11, wherein:  
the composite substance comprises 2 to 100 parts by weight of the solvent relative to 100 parts by weight of said metal particles.

Claim 15 (cancelled)

Claim 16 (previously amended): A conductive paste comprising:  
an organic binder;  
a composite substance comprising a solvent which is compatible with said organic binder, and metal-compound particles wetted by said solvent; and  
an organic solvent mixed with said organic binder and said composite substance, wherein said composite substance is prepared by mixing the solvent with undried metal-compound particles.

Claim 17 (cancelled)

Claim 18 (previously amended): The conductive paste of claim 16, wherein:  
said metal-compound particles have an average particle size of 1  $\mu\text{m}$  or smaller.

Claim 19 (previously amended): The conductive paste of claim 16, wherein:  
the composite substance comprises 2 to 100 parts by weight of the solvent relative to 100 parts by weight of said metal-compound particles.

Claim 20 (cancelled)

Claim 21 (currently amended): An electronic component comprising:  
a ceramic base body; and  
at least one electrode supported by said ceramic base body, wherein:  
said at least one electrode is formed from the conductive paste of claim 11.

Claim 22 (previously amended): An electronic component comprising:  
a ceramic base body; and  
at least one electrode supported by said ceramic base body, wherein:  
said at least one electrode is formed from the conductive paste of claim 16.

Claim 23 (previously amended): A method for manufacturing a composite substance used to form a conductive paste, comprising the step of:  
adding a solvent to undried metal particles which have been washed with water,  
wherein said solvent is compatible with an organic component included in said conductive paste and is incompatible with water, whereby said water is replaced by said solvent.

Claim 24 (previously amended): The method of claim 23, wherein:  
said solvent is added in an amount of 3 to 30 parts by weight relative to 100 parts by weight of the total quantity of said metal particles.

Claim 25 (previously amended): The method of claim 23, further comprising the step of:

adding a surface active agent together with said solvent, in an amount of 0.05 to 10.0 parts by weight relative to 100 parts by weight of the entire quantity of said metal particles.

Claim 26 (previously amended): The method of claim 25, further comprising the step of:

adding a second solvent which is compatible with water.

Claim 27 (previously amended): The method of claim 26, wherein:

said second solvent is added in an amount of 0.3 to 30 parts by weight relative to 100 parts by weight of the total quantity of said metal particles.

Claim 28 (previously amended): The method of claim 26, wherein:

said second solvent is acetone.

Claim 29 (currently amended): A method for manufacturing a composite substance ~~used to form a conductive paste~~, comprising the step of:

adding a solvent to undried metal-compound particles which have been washed with water, wherein said solvent is compatible with an organic binder and incompatible with water, whereby said water is replaced by said solvent.

Claim 30 (previously amended): The method of claim 29, wherein:

said solvent is added in an amount of 3 to 30 parts by weight relative to 100 parts by weight of the total quantity of said metal-compound particles.

Claim 31 (previously amended): The method of claim 29, further comprising the step of:

adding a surface active agent together with said solvent, in an amount of 0.05 to 10.0 parts by weight relative to 100 parts by weight of the entire quantity of said metal-compound particles.

Claim 32 (previously amended): The method of claim 31, further comprising the step of:

adding a second solvent which is compatible with water.

Claim 33 (previously amended): The method of claim 32, wherein:

said second solvent is added in an amount of 0.3 to 30 parts by weight relative to 100 parts by weight of the total quantity of said metal-compound particles.

Claim 34 (previously amended): The method of claim 32, wherein:

said second solvent is acetone.

Claim 35 (previously amended): A method for manufacturing a conductive paste, comprising the step of:

mixing an organic binder and an organic solvent with the composite substance of claim 23.

Claim 36 (previously amended): The method of claim 35, wherein:

said metal particles have an average particle size of 1  $\mu\text{m}$  or smaller.

Claim 37 (currently amended): The method of claim 35, wherein:  
the solvent ~~included in said composite substance~~ is present in an amount of 2 to 100 parts by weight units relative to 100 parts by weight of said metal particles.

Claim 38 (cancelled)

Claim 39 (previously amended): A method for manufacturing a conductive paste, comprising the step of:

mixing an organic binder and an organic solvent with the composite substance of Claim 29.

Claim 40 (previously amended): The method of claim 39, wherein:  
said metal-compound particles have an average particle size of 1  $\mu\text{m}$  or smaller.

Claim 41 (currently amended): The method of claim 39, wherein:  
the solvent ~~included in said composite substance~~ is present in an amount of 2 to 100 parts by weight relative to 100 parts by weight of said metal-compound particles.

Claims 42-58 (cancelled)

Claim 59 (currently amended): A composite substance ~~for a conductive paste~~ comprising:  
particles comprising a metal particle and a solvent, wherein said metal particle is wetted by said solvent, and said solvent is compatible with ~~an organic component included in said conductive paste~~ an organic binder and insoluble in water.

prepared by a process comprising:  
adding a solvent to undried metal particles which have been washed with water,  
thereby replacing said water by said solvent.

Claim 60 (cancelled).

Claim 61 (currently amended): A composite substance ~~for a conductive paste~~  
comprising:

particles comprising a metal-compound particle and a solvent,  
wherein said metal-compound particle is wetted by said solvent, and said solvent is  
compatible with ~~an organic component included in said conductive paste~~ an organic binder  
and incompatible with water,

prepared by a process comprising:  
adding a solvent to undried metal-compound particles which have been washed with  
water, thereby replacing said water by said solvent.

Claim 62 (cancelled).

Claim 63 (currently amended): A conductive paste comprising:  
an organic binder;  
a composite substance comprising particles comprising a metal particle and a solvent;  
and  
an organic solvent mixed with said organic binder and said composite substance;  
wherein said metal particle is wetted by said solvent, and said solvent is compatible  
with said organic binder and incompatible with water,



prepared by a process comprising:  
adding a solvent to undried metal particles which have been washed with water,  
thereby replacing said water by said solvent.

Claim 64 (cancelled)

Claim 65 (currently amended): A conductive paste comprising:  
an organic binder;  
a composite substance comprising particles comprising a metal-compound particle  
and a solvent; and  
an organic solvent mixed with said organic binder and said composite substance;  
wherein said metal-compound particle is wetted by said solvent, and said solvent is  
compatible with said organic binder and incompatible with water,  
prepared by a process comprising:  
adding a solvent to undried metal-compound particles which have been washed with  
water, thereby replacing said water by said solvent.

Claim 66 (cancelled)

Claim 67 (previously added): An electronic component comprising:  
a ceramic base body; and  
at least one electrode supported by said ceramic base body,  
wherein said at least one electrode is prepared from the conductive paste of claim 63.

Claim 68 (cancelled)

Claim 69 (previously added): An electronic component comprising:  
a ceramic base body; and  
at least one electrode supported by said ceramic base body,  
wherein said at least one electrode is prepared from the conductive paste of claim 65.

Claim 70 (cancelled)